



Fast Recovery Rectifiers

Reverse Voltage - 50 to 1000 Volts Forward Current - 6.0 Amperes



R-6

FR601~ FR607

R6 Leaded Plastic Package RoHS compliant

FEATURES:

- 1. Fast switching for high efficiency
- 2. Low reverse leakage.
- 3. High forward surge current capability
- 4. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER		SYMBOL	FR 601	FR 602	FR 603	FR 604	FR 605	FR 606	FR 607	UNIT
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current 0.375" (9.5mm) lead length @T₄=75°C		I _(AV)	6.0				Α			
Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load		I _{FSM}	300				Α			
Maximum Instantaneous Forward Voltage at 6.0A		V_{F}	1.3				V			
Maximum DC Reverse Current	@ T _A =25°C		10.0							
at Rated DC Blocking Voltage	@ T _A =100°C	I _R 200.0			μA					
Maximum reverse recovery time ¹		t _{rr}		15	50		250	50	00	ns
Typical Junction Capacitance ²		C_J	150				pF			
Typical Thermal Resistance ³		R_{qJA}	10				°C/W			
Operating Temperature Range Storage Temperature Range		T_J, T_{STG}	-65 to +150			°C				

Note:

- 1. Reverse recovery condition I_F =0.5A, I_R =1.0A, I_{RR} =0.25A
- 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- 3. Thermal resistance from junction to ambient at 0.375*0.375" (9.5mm) lead length, P.C.B. mounted.





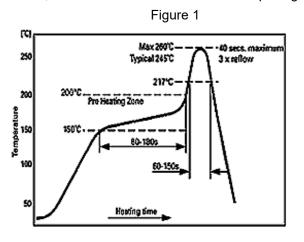


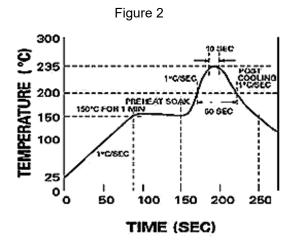
Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.





Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat – Temperature Range – Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds
Time maintained above: – Temperature – Time	200°C 30-50 seconds	217°C 60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.







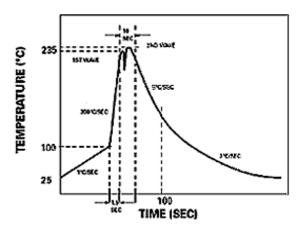
Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

TEMPERATURE (C) 260 C18C C) 26

TIME (SEC)

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-Free System		
Average Ramp-Up Rate	~200°C/second	~200°C/second		
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec		
Final preheat Temperature	Within 125°C of Solder	Within 125°C of Solder Temp		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	10 seconds		
Ramp-Down Rate	5°C/second max.	5°C/second max		





TYPICAL CHARACTERISTICS CURVE

Fig 1: Forward Current Derating Curve

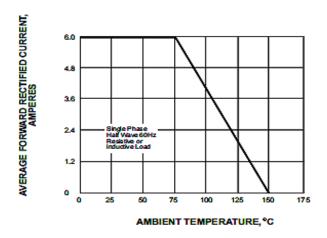
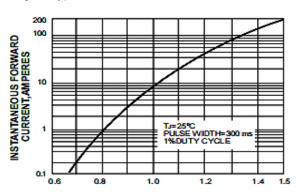


Fig 3: Typical Instantaneous Forward Characteristics



INSTANTANEOUS FORWARD VOLEAGE, VOLTS

Fig 5: Typical Junction Capacitance

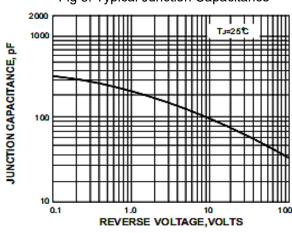


Fig 2: Maximum Non-Repetitive Peak Forward Surge Current

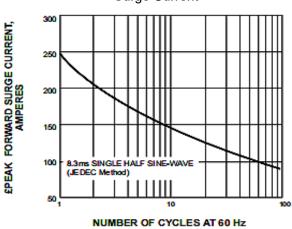
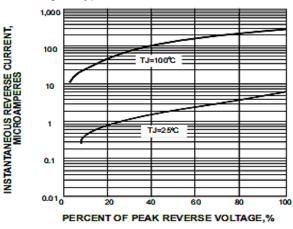
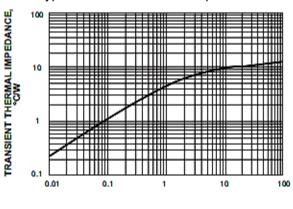


Fig 4: Typical reverse characteristics



Typical Transient thermal Impedance



t,PULSE DURATION,sec.

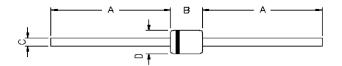






PACKAGE DETAILS

R6 Leaded Plastic Package



DIM	MIN	MAX
Α	25.4	-
В	8.6	9.1
C	1.2	1.3
D	8.6	9.1

All Dimensions are in mm

Note: Cathode is marking by Band







Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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